PCN: TongFu Microelectronics Co., Ltd (TFME) as a Subcontractor for the Assembly of 32L QFN package

Zilog, Inc.
1590 Buckeye Drive
Milpitas, CA 95035-7418

April 12, 2021

Subject: TongFu Microelectronics Co., Ltd (TFME) as a Subcontractor for the
Assembly of 32L QFN package.

Dear Valued Customer and/or Distributor:

We would like to inform you that we have qualified TongFu Microelectronics Co., Ltd (TFME) for the assembly of the 32L QFN package using our standard qualification process (please see the attached qualification data).

TongFu Microelectronics Co., Ltd (TFME) is a previously existing qualified package Subcontractors.

Should you have questions on this matter or need additional assistance, please contact csr@zilog.com.

Thank you for your continued interest in Zilog products and services.

Sincerely,

Alan Shaw
AShaw@littelfuse.com
VP of Operations MCU
Zilog: a Littelfuse Company

RELIABILITY TEST DATA:	**REJ/SS**
WIRE PULL	0/10
BALL SHEAR	0/3
DIE SHEAR	0/1
EXTERNAL VISUAL	0/125
PRECONDITIONING (30ºC, 60%RH, 192 HRS)	0/135
PRESSURE POT (121ºC, 100%RH, 2 ATM, 168 HRS)	0/45
TEMPERATURE CYCLE (-65ºC, 150ºC, 500X)	0/45
Biased HAST, 96 HRS	0/42
HTS (150ºC, 168 HRS)	0/77
ZILOG QUALIFICATION REPORT	21012621